

**OptiMOS™-5 Power-Transistor**

**Features**

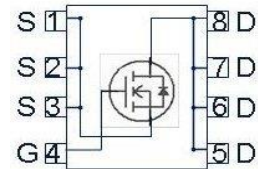
- N-channel - Enhancement mode - Logic level
- AEC qualified
- MSL1 up to 260°C peak reflow
- 100% Avalanche tested
- Feasible for automatic optical inspection (AOI)

**Product Summary**

$V_{DS}$	100	V
$R_{DS(on)}$	4	mΩ
$I_D$	100	A

**PG-TDSON-8**


Type	Package	Marking
IAUC100N10S5L040	PG-TDSON-8	5N10L040


**Maximum ratings, at  $T_j=25\text{ °C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current <sup>1)</sup>	$I_D$	$T_C=25\text{ °C}, V_{GS}=10\text{V}$	100	A
		$T_C=100\text{ °C}, V_{GS}=10\text{V}$	100	
Pulsed drain current <sup>2)</sup>	$I_{D,pulse}$	$T_C=25\text{ °C}$	400	
Avalanche energy, single pulse	$E_{AS}$	$I_D=50\text{A}$	150	mJ
Avalanche current, single pulse	$I_{AS}$	-	86	A
Gate source voltage	$V_{GS}$	-	±20	V
Power dissipation	$P_{tot}$	$T_C=25\text{ °C}, T_J=175\text{ °C}$	167	W
Operating and storage temperature	$T_j, T_{stg}$	-	-55 ... +175	°C

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Thermal characteristics**

Thermal resistance, junction - case	$R_{thJC}$	-	-	-	0.9	K/W
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**Electrical characteristics, at  $T_j=25\text{ °C}$ , unless otherwise specified**
**Static characteristics**

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=1mA$	100	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=90\mu A$	1.2	1.7	2.2	
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=100V, V_{GS}=0V, T_j=25\text{ °C}$	-	0.1	1	$\mu A$
		$V_{DS}=100V, V_{GS}=0V, T_j=125\text{ °C}^{2)}$	-	10	100	
Gate-source leakage current	$I_{GSS}$	$V_{GS}=20V, V_{DS}=0V$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=50\text{ A}$	-	4.3	5.7	m $\Omega$
		$V_{GS}=10\text{ V}, I_D=50\text{ A}$	-	3.3	4	
Gate resistance <sup>2)</sup>	$R_G$		-	1.3	-	$\Omega$

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Dynamic characteristics<sup>2)</sup>**

Input capacitance	$C_{iss}$	$V_{GS}=0\text{ V}, V_{DS}=50\text{ V}, f=1\text{ MHz}$	-	4000	5200	pF
Output capacitance	$C_{oss}$		-	660	860	
Reverse transfer capacitance	$C_{rss}$		-	28	42	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=50\text{ V}, V_{GS}=10\text{ V}, I_D=100\text{ A}, R_G=3.5\Omega$	-	6	-	ns
Rise time	$t_r$		-	3	-	
Turn-off delay time	$t_{d(off)}$		-	30	-	
Fall time	$t_f$		-	21	-	

**Gate Charge Characteristics<sup>2)</sup>**

Gate to source charge	$Q_{gs}$	$V_{DD}=50\text{ V}, I_D=50\text{ A}, V_{GS}=0\text{ to }10\text{ V}$	-	13	16	nC
Gate to drain charge	$Q_{gd}$		-	11	16	
Gate charge total	$Q_g$		-	60	78	
Gate plateau voltage	$V_{plateau}$		-	3.0	-	V

**Reverse Diode**

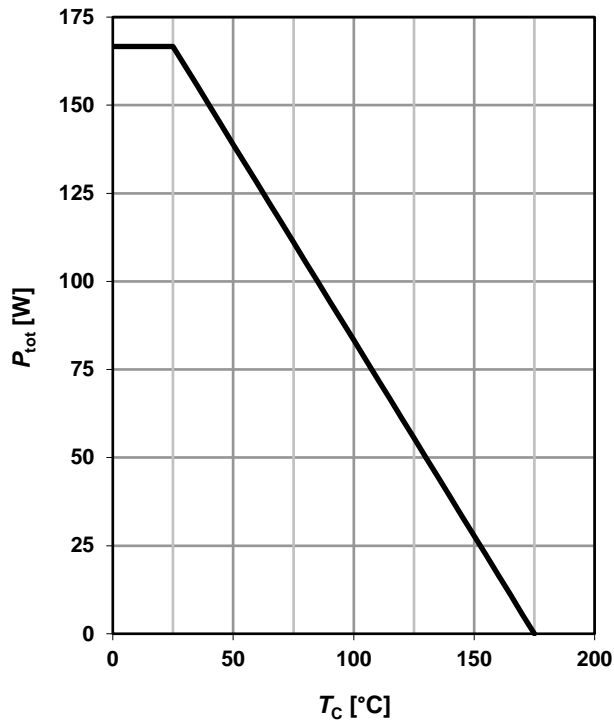
Diode continuous forward current <sup>2)</sup>	$I_S$	$T_C=25^\circ\text{ C}$	-	-	100	A
Diode pulse current <sup>2)</sup>	$I_{S,pulse}$		-	-	400	
Diode forward voltage	$V_{SD}$	$V_{GS}=0\text{ V}, I_F=50\text{ A}, T_j=25^\circ\text{ C}$	-	0.9	1.1	V
Reverse recovery time <sup>2)</sup>	$t_{rr}$	$V_R=50\text{ V}, I_F=50\text{ A}, di_F/dt=100\text{ A}/\mu\text{ s}$	-	61	-	ns
Reverse recovery charge <sup>2)</sup>	$Q_{rr}$		-	92	-	nC

<sup>1)</sup> Current is limited by package; with an  $R_{thJC}=0.9\text{ K/W}$  the chip is able to carry 140A at 25°C.

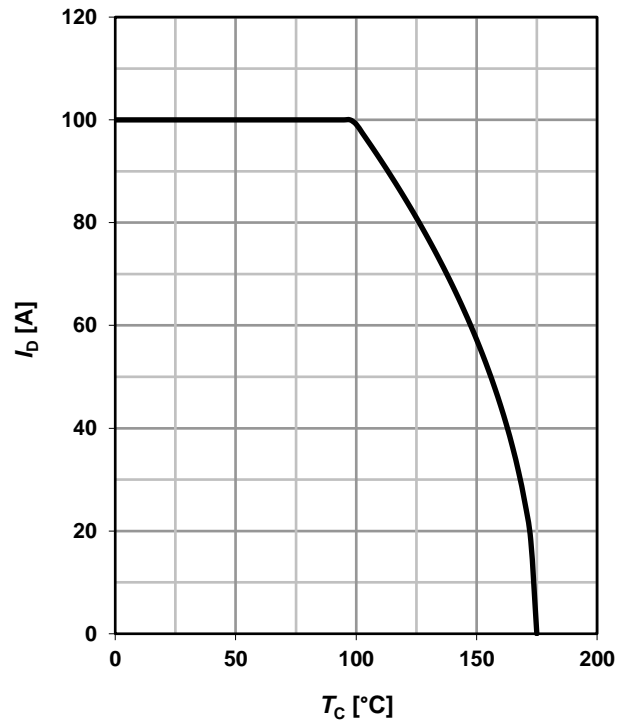
<sup>2)</sup> Defined by design. Not subject to production test.

**1 Power dissipation**

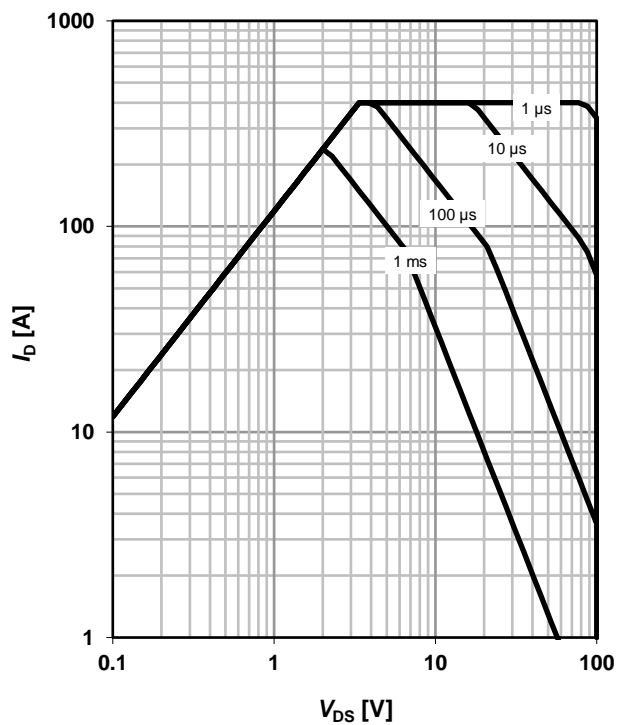
$$P_{\text{tot}} = f(T_C); V_{\text{GS}} \geq 6 \text{ V}$$


**2 Drain current**

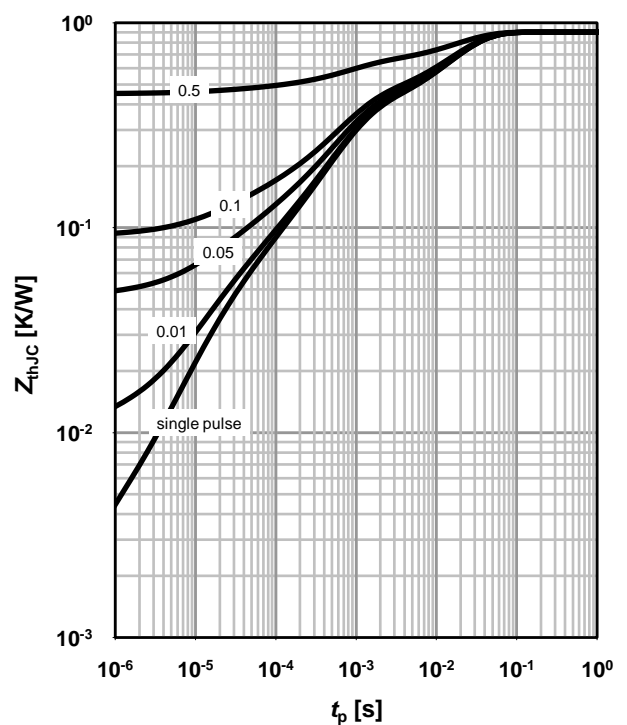
$$I_D = f(T_C); V_{\text{GS}} \geq 6 \text{ V}$$


**3 Safe operating area**

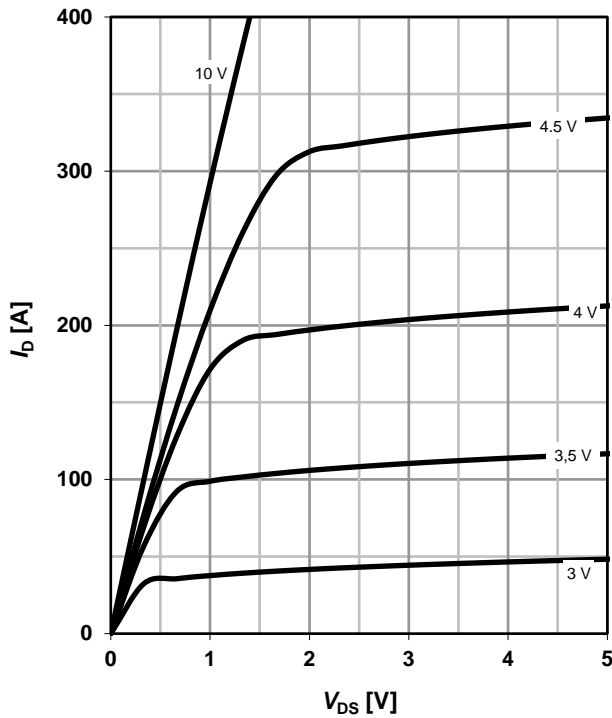
$$I_D = f(V_{\text{DS}}); T_C = 25 \text{ °C}; D = 0$$

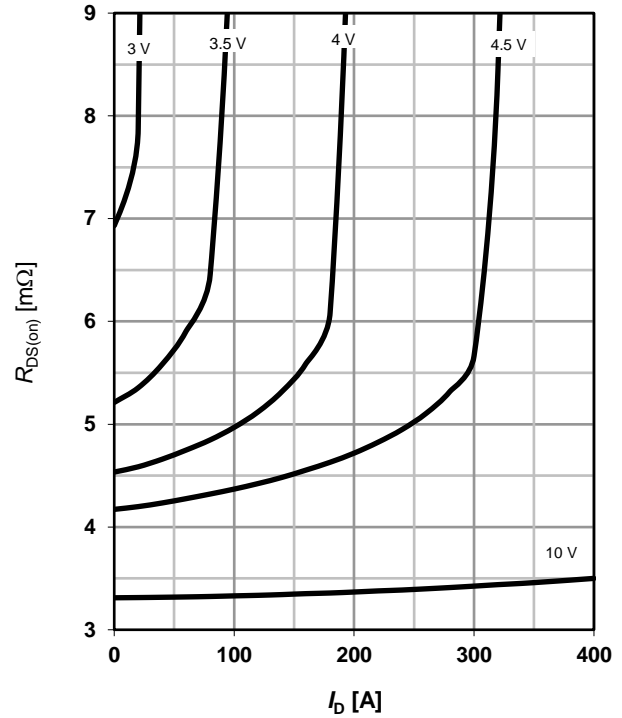
 parameter:  $t_p$ 

**4 Max. transient thermal impedance**

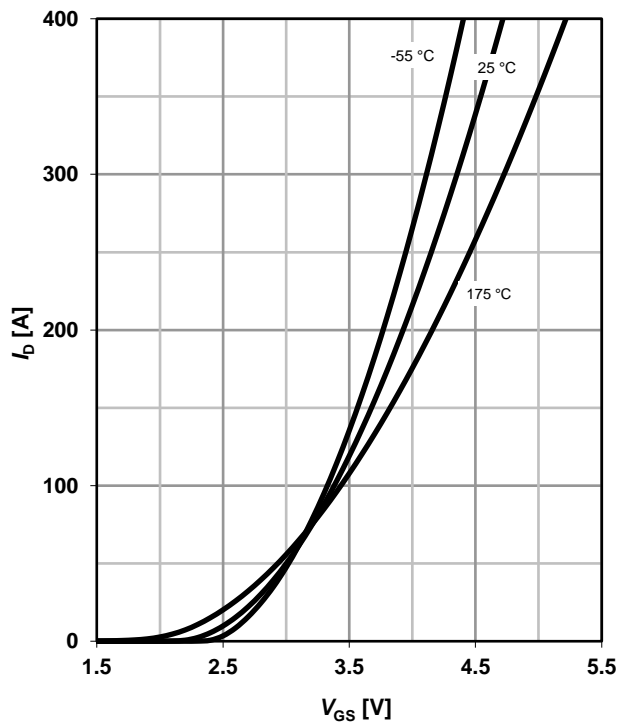
$$Z_{\text{thJC}} = f(t_p)$$

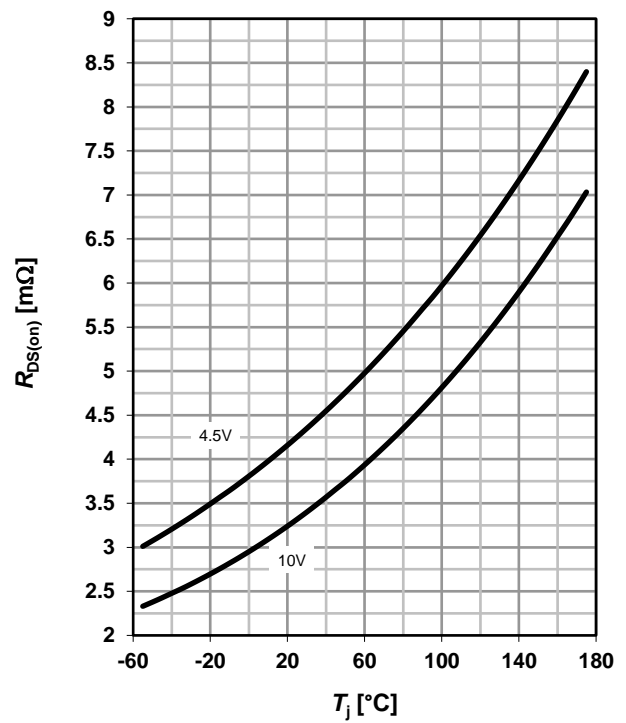
 parameter:  $D = t_p/T$ 


**5 Typ. output characteristics**
 $I_D = f(V_{DS}); T_j = 25\text{ °C}$ 

 parameter:  $V_{GS}$ 

**6 Typ. drain-source on-state resistance**
 $R_{DS(on)} = f(I_D); T_j = 25\text{ °C}$ 

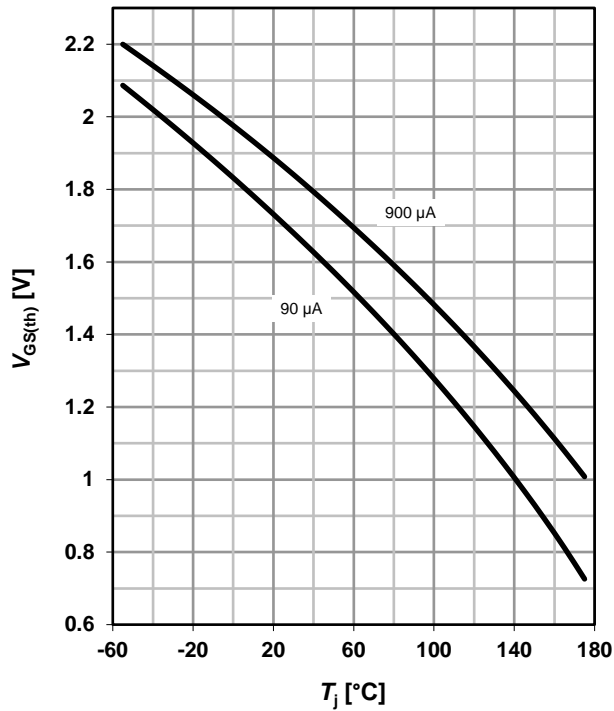
 parameter:  $V_{GS}$ 

**7 Typ. transfer characteristics**
 $I_D = f(V_{GS}); V_{DS} = 6V$ 

 parameter:  $T_j$ 

**8 Typ. drain-source on-state resistance**
 $R_{DS(on)} = f(T_j); I_D = 50\text{ A}$ 

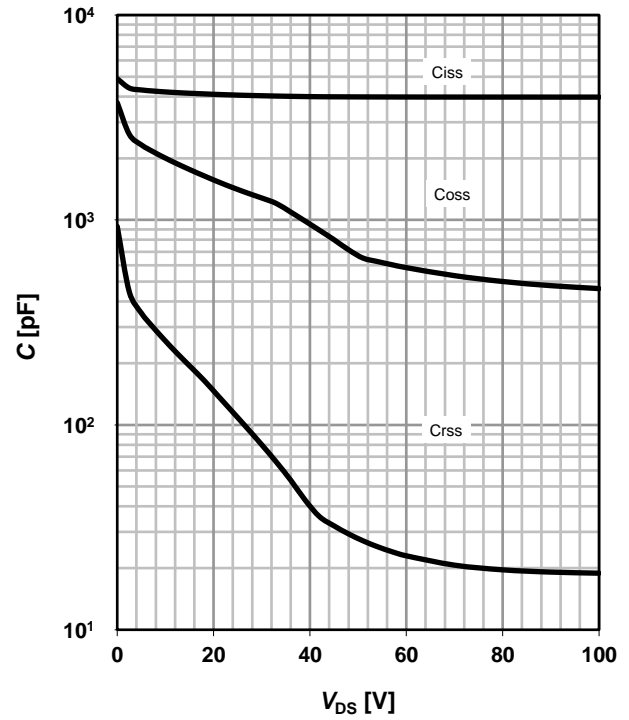
 parameter:  $V_{GS}$ 


**9 Typ. gate threshold voltage**

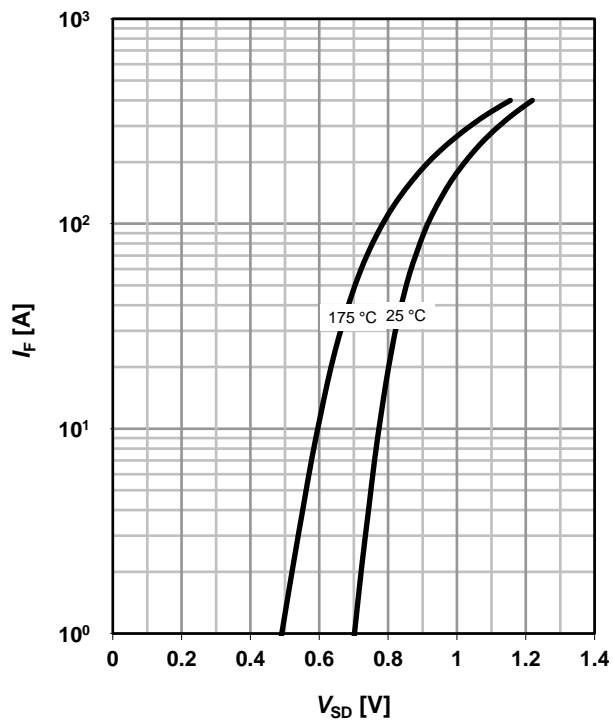
$$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$$

 parameter:  $I_D$ 

**10 Typ. capacitances**

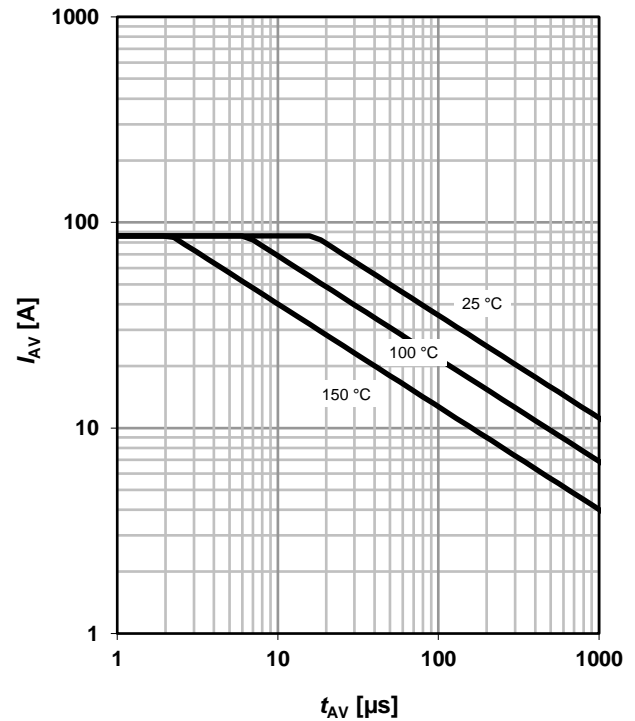
$$C = f(V_{DS}); V_{GS} = 0 V; f = 1 MHz$$


**11 Typical forward diode characteristics**

$$I_F = f(V_{SD})$$

 parameter:  $T_j$ 

**12 Typ. avalanche characteristics**

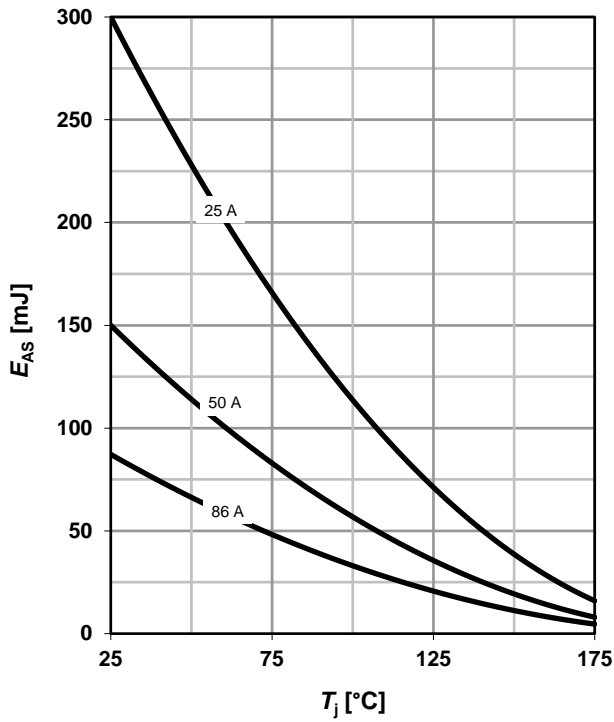
$$I_{AS} = f(t_{AV})$$

 parameter:  $T_{j(start)}$ 


**13 Typical avalanche energy**

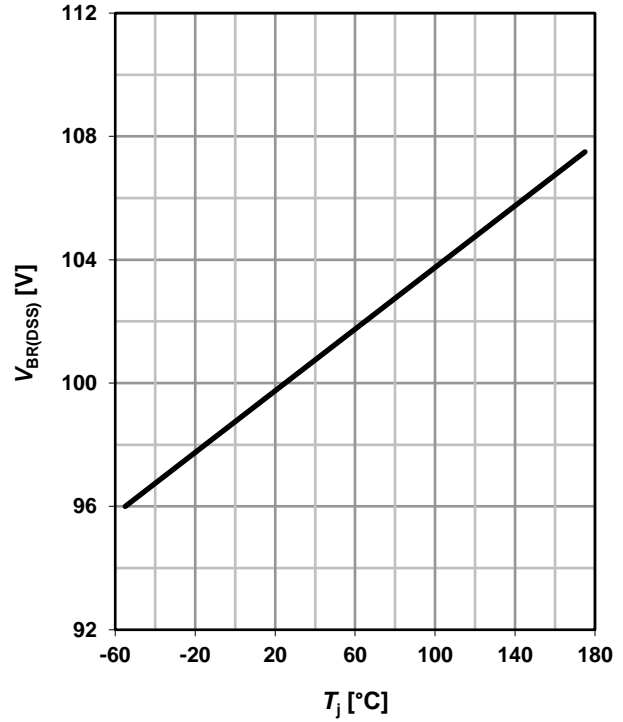
$$E_{AS} = f(T_j)$$

parameter:  $I_D$



**14 Drain-source breakdown voltage**

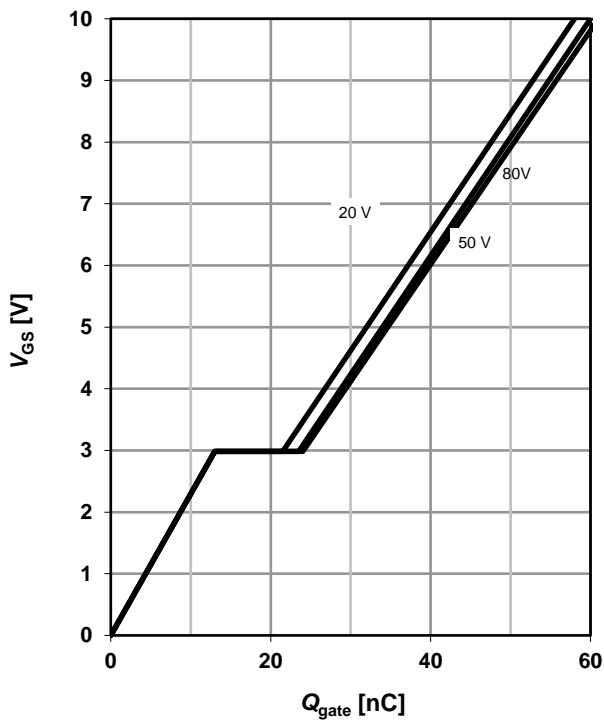
$$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$$



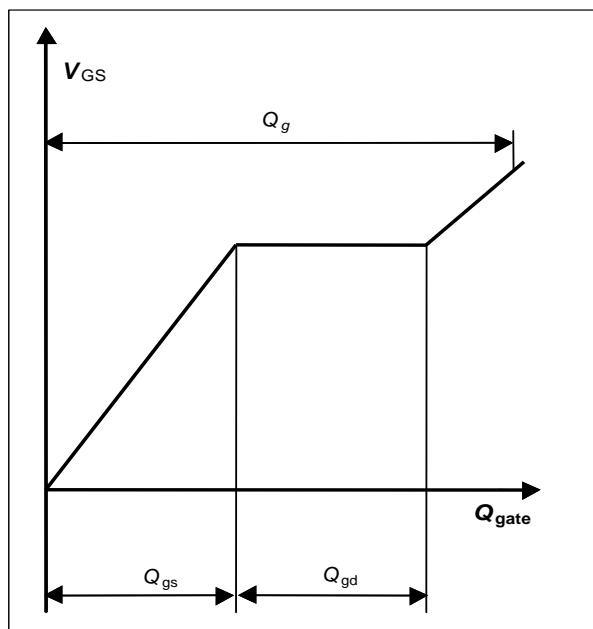
**15 Typ. gate charge**

$$V_{GS} = f(Q_{gate}); I_D = 50 \text{ A pulsed}$$

parameter:  $V_{DD}$



**16 Gate charge waveforms**



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## Revision History

Version	Date	Changes
Revision 1.0	12.06.2018	Final Data Sheet

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